

Fuseholder Open Design, 5 x 20 mm, SMD, var. Covers, IEC 60335-1



OGN-SMD



OGN-SMD for increased solder temperature with gold contacts



OGN-SMD equipped with fuse



OGN-SMD equipped with fuse

500 VAC · 4 W/16 A (VDE) · 500 V · 16 A (UL/CSA)

See below:
[Approvals and Compliances](#)

Description

- For appliances in unattended use

Unique Selling Proposition

- Suitable for fully automated PCD assembling
- Available with blister tape packaging
- Small design height
- Available preassembled with fuses


Applications

- Household appliances

Weblinks

[pdf datasheet](#), [html-datasheet](#), [General Product Information](#), [Packaging details](#), [Distributor-Stock-Check](#), [Accessories](#), [Detailed request for product](#), [Microsite](#)

Technical Data

| | |
|------------------------------|---|
| Shock-Safe Category | PC1 |
| Fuse-Link | 5 x 20 mm |
| Mounting | PCB |
| Terminal | Solder SMT |
| Rated Voltage | 500VAC (VDE), 500V (UL/CSA) |
| Rated current | 10/16A (VDE), 16A (UL/CSA) |
| Rated Power Acceptance IEC | 4 W / 16 A @ Ta 23 °C 4 W / 10 A with black cover 2.5 W / 10 A with transparent cover, see derating curves |
| Degree of Protection | IP 20 (with cover) |
| Protection Class | Suitable for appliances with protection class I acc. to IEC 61140 |
| Admissible Ambient Air Temp. | -40 °C to 85 °C |
| Climatic Category | 40/085/21 acc. to IEC 60068-1 |
| Material: Socket | see variants |
| Material: Cover | Thermoplastic UL 94V-0 |
| Material: Terminals | Tin-Plated Copper Alloy |
| Unit Weight | 1.7 g |
| Storage Conditions | 0 °C to 60 °C, max. 70% r.h. |
| Product Marking |  Type, Rated Voltage, Rated current, Power Rating, Approvals |

| | |
|---------------------------|---|
| Soldering Methods | Reflow (lead-free) Soldering Profile |
| Solderability | 245-260 °C / max. 30 sec acc. to JEDEC J-STD-020D |
| Contact Resistance | ≤ 10 mΩ at 20 mV acc. to IEC 60127-6 |
| Dielectric Strength | > 3kV between life parts (50Hz: 1 min) |
| Impulse Withstand Voltage | > 4kV between life parts |
| Insulation Resistance | ≥ 10 MΩ (500 VDC: 1 min) |
| Overvoltage Category | III acc. to IEC 60664-1 |
| Pollution Degree | 3 acc. to IEC 60664-1 |




Approvals and Compliances

Detailed information on product approvals, code requirements, usage instructions and detailed test conditions can be looked up in [Details about Approvals](#)

Approvals

The approval mark is used by the testing authorities to certify compliance with the safety requirements placed on electronic products.

Approval Reference Type: OGN-SMD

| Approval Logo | Certificates | Certification Body | Description |
|---|---------------|--------------------|----------------------------------|
|  | VDE Approvals | VDE | VDE Certificate Number: 40001042 |
|  | VDE Approvals | VDE | VDE Certificate Number: 40045404 |
|  | UL Approvals | UL | UL File Number: E39328 |



Product standards

Product standards that are referenced

| Organization | Design | Standard | Description |
|--|-----------------------|----------------------|--|
|  | Designed according to | IEC 60127-6 | Miniature fuses. Part 6. Fuse-holders for miniature fuse-links |
|  | Designed according to | UL 4248-1 | Fuseholder general requirements |
|  | Designed according to | CSA C22.2 no. 4248.1 | Fuseholder general requirements |






Application standards

Application standards where the product can be used

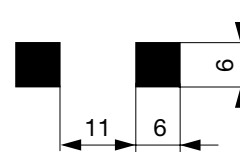
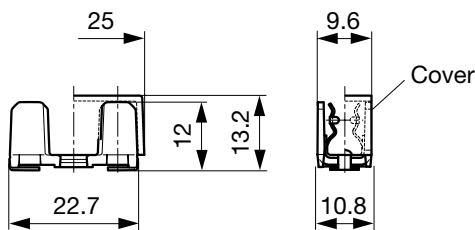
| Organization | Design | Standard | Description |
|--|--------------------------------|--------------|---|
|  | Designed for applications acc. | IEC/UL 60950 | IEC 60950-1 includes the basic requirements for the safety of information technology equipment. |
|  | Designed for applications acc. | IEC 60335-1 | Safety of electrical appliances for household and similar purposes. Meets the requirements for appliances in unattended use. This includes the enhanced requirements of glow wire tests acc. to IEC 60695-2-12 and -13. |

Compliances

The product complies with following Guide Lines

| Identification | Details | Initiator | Description |
|--|------------------------------|-------------|---|
|  | CE declaration of conformity | SCHURTER AG | The CE marking declares that the product complies with the applicable requirements laid down in the harmonisation of Community legislation on its affixing in accordance with EU Regulation 765/2008. |
|  | RoHS | SCHURTER AG | EU Directive RoHS 2011/65/EU |
|  | China RoHS | SCHURTER AG | The law SJ / T 11363-2006 (China RoHS) has been in force since 1 March 2007. It is similar to the EU directive RoHS. |
|  | REACH | SCHURTER AG | On 1 June 2007, Regulation (EC) No 1907/2006 on the Registration, Evaluation, Authorization and Restriction of Chemicals 1 (abbreviated as "REACH") entered into force. |
|  | White paperGlow wire test | SCHURTER AG | Meets the requirements of IEC 60335-1 for appliances in unattended use. This includes the enhanced requirements of glow wire tests acc. to IEC 60695-2-12 and -13. |

Dimension [mm]



Soldering pads

Derating Curves

With Transparent Cover



Order numbers for pre-assembled OGN-SMD, blister tape packaging with 400 pieces per reel

| Rated current In | FTT 5x20 with reflow cover 0853.0571 | FTT 5x20 no cover | FST 5x20 with reflow cover 0853.0571 | FST 5x20 no cover | FSF 5x20 with reflow cover 0853.0571 | FSF 5x20 no cover | SMD-SPT 5x20 with reflow cover 0853.0571 | SMD-SPT 5x20 no cover |
|------------------|--------------------------------------|-------------------|--------------------------------------|-------------------|--------------------------------------|-------------------|--|-----------------------|
| 50 mA | | | 0031.8304 | 0031.8354 | | | | |
| 63 mA | 0031.8501 | 0031.8551 | 0031.8305 | 0031.8355 | | | | |
| 80 mA | 0031.8502 | 0031.8552 | 0031.8306 | 0031.8356 | | | | |
| 100 mA | 0031.8503 | 0031.8553 | 0031.8307 | 0031.8357 | | | | |
| 125 mA | 0031.8504 | 0031.8554 | 0031.8308 | 0031.8358 | | | | |
| 160 mA | 0031.8505 | 0031.8555 | 0031.8309 | 0031.8359 | | | | |
| 200 mA | 0031.8506 | 0031.8556 | 0031.8310 | 0031.8360 | | | | |
| 250 mA | 0031.8507 | 0031.8557 | 0031.8311 | 0031.8361 | | | | |
| 315 mA | 0031.8508 | 0031.8558 | 0031.8312 | 0031.8362 | | | | |
| 400 mA | 0031.8509 | 0031.8559 | 0031.8313 | 0031.8363 | | | | |
| 500 mA | 0031.8510 | 0031.8560 | 0031.8314 | 0031.8364 | 0031.8413 | 0031.8463 | | |
| 630 mA | 0031.8511 | 0031.8561 | 0031.8315 | 0031.8365 | 0031.8414 | 0031.8464 | | |
| 800 mA | 0031.8512 | 0031.8562 | 0031.8316 | 0031.8366 | 0031.8415 | 0031.8465 | | |
| 1 A | 0031.8513 | 0031.8563 | 0031.8317 | 0031.8367 | 0031.8416 | 0031.8466 | 0031.8993 | 0031.9007 |
| 1,25 A | 0031.8514 | 0031.8564 | 0031.8318 | 0031.8368 | 0031.8417 | 0031.8467 | 0031.8994 | 0031.9008 |
| 1,6 A | 0031.8515 | 0031.8565 | 0031.8319 | 0031.8369 | 0031.8418 | 0031.8468 | 0031.8995 | 0031.9009 |
| 2A | 0031.8516 | 0031.8566 | 0031.8320 | 0031.8370 | 0031.8419 | 0031.8469 | 0031.8996 | 0031.9010 |
| 2,5 A | 0031.8517 | 0031.8567 | 0031.8321 | 0031.8371 | 0031.8420 | 0031.8470 | 0031.8997 | 0031.9011 |
| 3,15 A | 0031.8518 | 0031.8568 | 0031.8322 | 0031.8372 | 0031.8421 | 0031.8471 | 0031.8998 | 0031.9012 |
| 4 A | 0031.8519 | 0031.8569 | 0031.8323 | 0031.8373 | 0031.8422 | 0031.8472 | 0031.8999 | 0031.9013 |
| 5 A | | | 0031.8324 | 0031.8374 | 0031.8423 | 0031.8473 | 0031.9000 | 0031.9014 |
| 6,3 A | | | 0031.8325 | 0031.8375 | 0031.8424 | 0031.8474 | 0031.9001 | 0031.9015 |
| 8 A | | | 0031.8326 | 0031.8376 | 0031.8425 | 0031.8475 | 0031.9002 | 0031.9016 |
| 10 A | | | 0031.8327 | 0031.8377 | 0031.8426 | 0031.8476 | 0031.9003 | 0031.9017 |

All fuses in the pre-assembled OGN-SMD fuseholders are suitable for the reflow solder process.

All Variants

| Holder | Material | Material: Terminals | Reflow Condition | Packaging | Order Number |
|--------|---------------------|--------------------------|---|--------------------------------------|--------------|
| ● | Thermoplastic | Tin-Plated Copper Alloy | acc. to JEDEC J-STD-020D, Tp=245 +0/-5 °C, tp = max. 30 s | Bulk 128 x 91 x 60 mm (100 pcs.) | 0031.8221 |
| ● | Thermoplastic | Tin-Plated Copper Alloy | acc. to JEDEC J-STD-020D, Tp=245 +0/-5 °C, tp = max. 30 s | Blister Tape 38 cm Reel (400 pcs.) | 0031.8225 |
| ● | Thermoplastic | Tin-Plated Copper Alloy | acc. to JEDEC J-STD-020D, Tp=245 +0/-5 °C, tp = max. 30 s | Blister Tray 266 x 174 mm (500 pcs.) | 0031.8222 |
| ● | Spec. Thermoplastic | Tin-Plated Copper Alloy | acc. to JEDEC J-STD-020D, Tp=260 +0/-5 °C, tp = max. 30 s | Bulk 128 x 91 x 60 mm (100 pcs.) | 0031.8263 |
| ● | Spec. Thermoplastic | Tin-Plated Copper Alloy | acc. to JEDEC J-STD-020D, Tp=260 +0/-5 °C, tp = max. 30 s | Blister Tape 38 cm Reel (400 pcs.) | 0031.8265 |
| ● | Spec. Thermoplastic | Tin-Plated Copper Alloy | acc. to JEDEC J-STD-020D, Tp=260 +0/-5 °C, tp = max. 30 s | Blister Tray 266 x 174 mm (500 pcs.) | 0031.8264 |
| ● | Spec. Thermoplastic | Gold-Plated Copper Alloy | acc. to JEDEC J-STD-020D, Tp=260 +0/-5 °C, tp = max. 30 s | Bulk 128 x 91 x 60 mm (100 pcs.) | 0031.8273 |
| ● | Spec. Thermoplastic | Gold-Plated Copper Alloy | acc. to JEDEC J-STD-020D, Tp=260 +0/-5 °C, tp = max. 30 s | Blister Tape 38 cm Reel (400 pcs.) | 0031.8275 |
| ● | Spec. Thermoplastic | Gold-Plated Copper Alloy | acc. to JEDEC J-STD-020D, Tp=260 +0/-5 °C, tp = max. 30 s | Blister Tray 266 x 174 mm (500 pcs.) | 0031.8274 |

Most Popular.

Availability for all products can be searched real-time: <https://www.schurter.com/en/Stock-Check/Stock-Check-SCHURTER>

The fuseholder is suitable for use in equipment according to IEC 60335-1.

Fuseholders with gold-plated terminals are more heat resistant than fuseholders with tin-plated terminals.

If soldering problems occur with the thermoplastic version, it is recommended to use the spec. thermoplastic with tin-plated and gold-plated terminals.

Packaging Unit see variants

Accessories

Description



Covers for OGN, OGN-SMD
 Cover for Holder OGN, OGN-SMD



Adapter to OGN, OGN-SMD
 Fuse Carriage with Handle for OGN, OGN-SMD